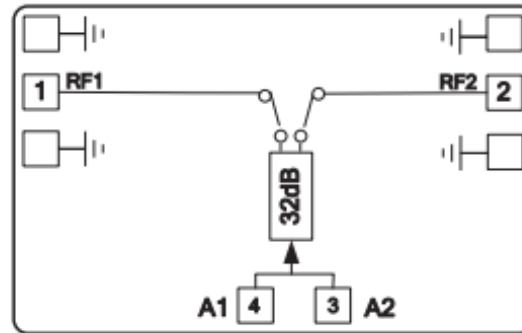


Features

- Attenuation Range: 32dB
- Attenuation Accuracy: ± 1 dB
- Insertion Loss : 2.6dB
- Impedance: 50 Ω
- Die Size: 1.0 x 1.0 x 0.1 mm

Typical Applications

- Test Instrumentation
- Microwave Radio & VSAT
- Military & Space
- Telecom Infrastructure
- Fiber Optics

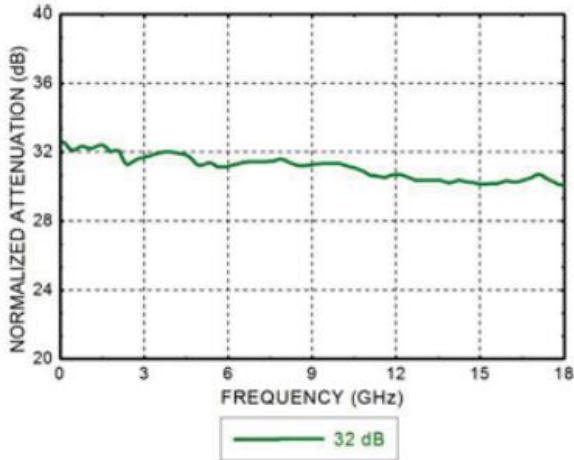
Functional Block Diagram

Electrical Specifications

TA = +25°C, Vctl = 0/-5V

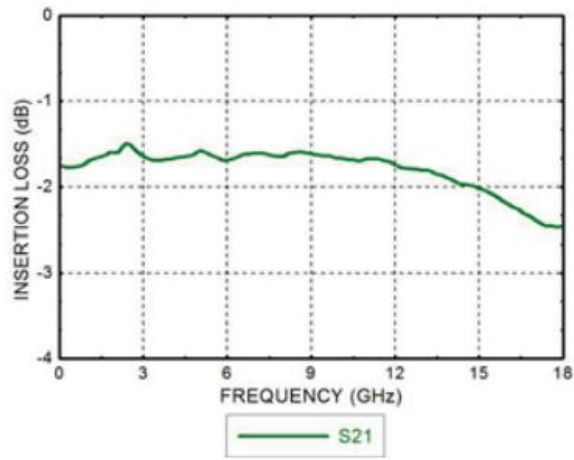
Parameters	Min.	Typ.	Max.	Units
Frequency	0.5-18			GHz
Insertion Loss		2.6		dB
Attenuation Range		32		dB
Return Loss		18		dB
Input 1dB Compression (P1dB)		24		dBm
Switching Speed		30		ns



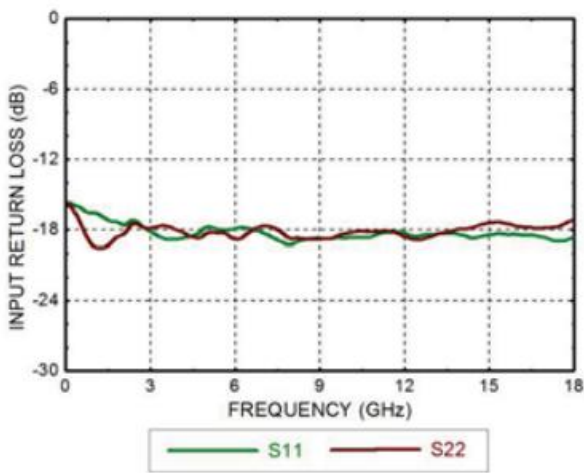
Attenuation



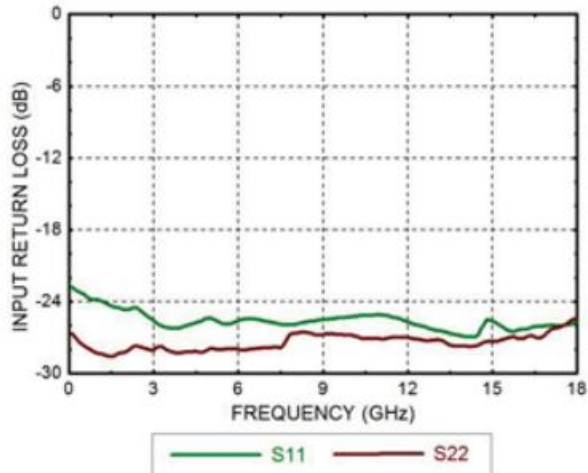
Insertion Loss



Return Loss



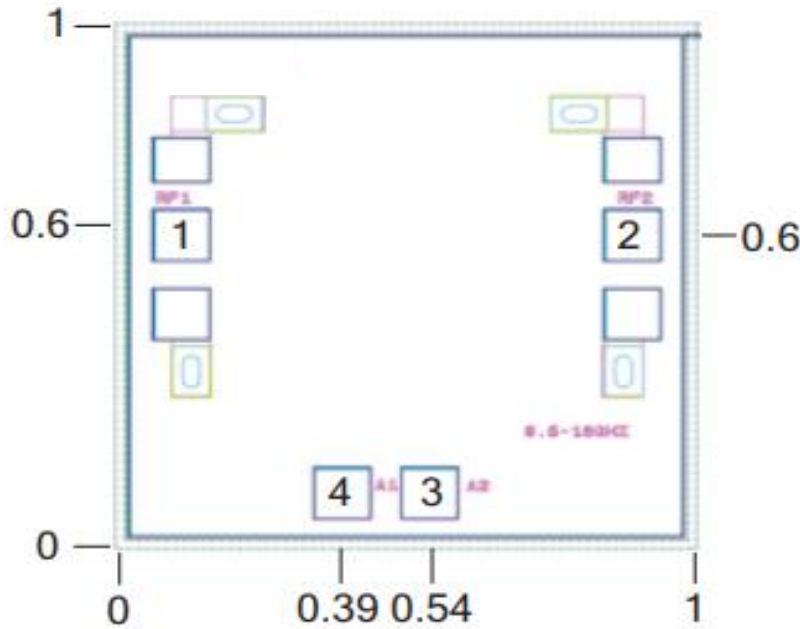
Attenuation Return Loss





Outline Drawing:

All Dimensions in mm

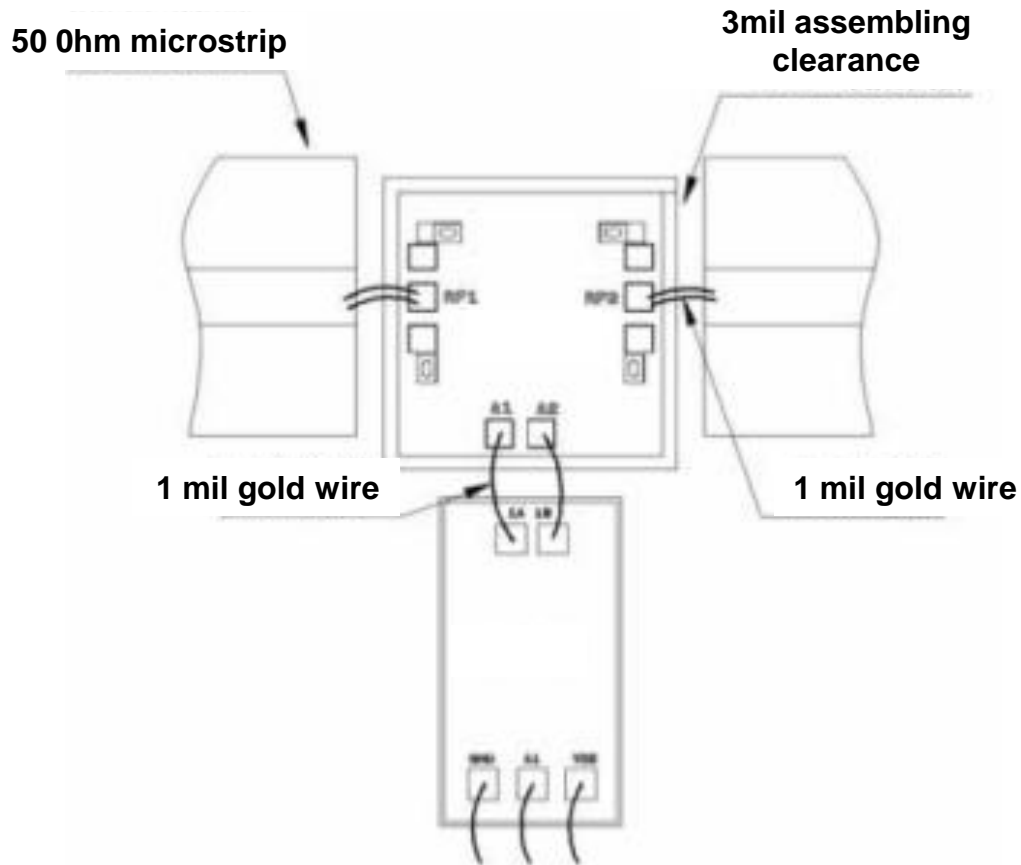


Pad Description

PAD	Function	Description
1	RF1	This pad is RF port and matched to 50Ω Impedance
2	RF2	This pad is RF port and matched to 50Ω Impedance
3, 4	A2, A1	A 2= -5 V, A1= 0 V, pass-through ; A2=0V,A1= -5V, decaying 32dB.
Die Bottom	GND	Die bottom must be connected to RF/DC ground



Assembly Drawing



Notes:

1. Die thickness: 100um
2. Typical bond pad is 100*100 μm^2
3. Bond pad metalization: Gold
4. Backside metalization: Gold
5. Backside of the die (GND)
6. No connection required for unlabeled bond pads

Maximum Ratings:

1. RF input power: +24dBm
2. Storage temperature: -65°C to +175°C
3. Operating temperature: -55°C to +85°C